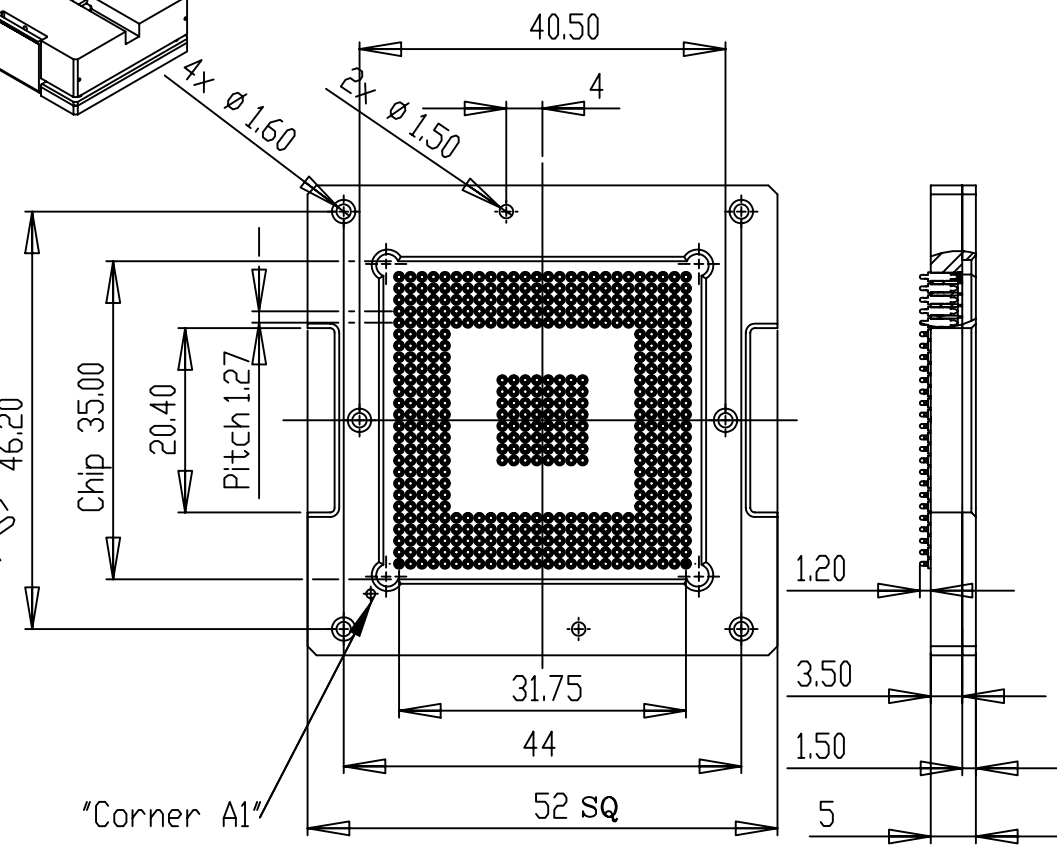
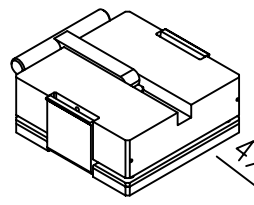
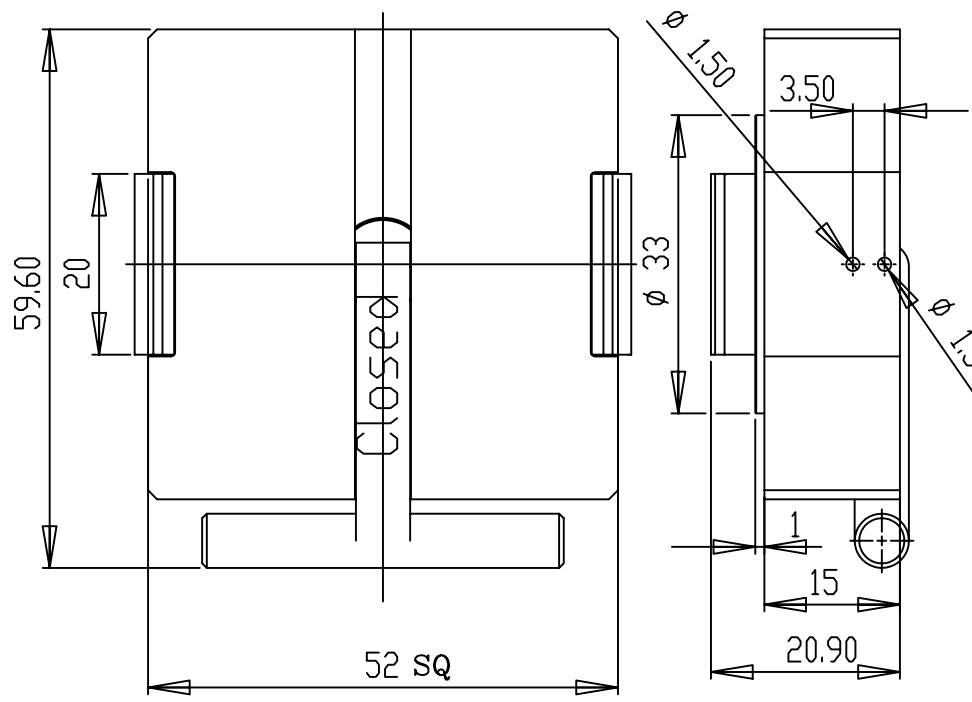


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	08/17/05	H.N.
B	UPDATED PACKAGE DIM	08/30/05	H.N.

SKT2392

RETENTION FRAME

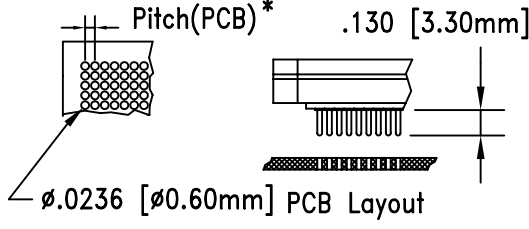
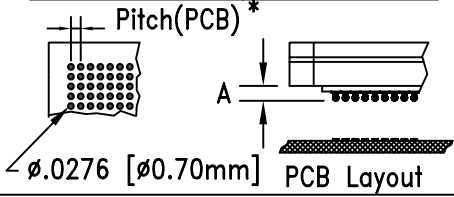


SOCKET

RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE	RAISED SMT STYLE
XX = (-SM)	XX = (-SR)
YY = (-30)	YY = (-29)

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET)
YY = (-70)



30= standard SMD ("A" = .047 [1.20mm])
 29= raised SMD ("A" = .197 [5.00mm])
 BALL DIAMETER FOR:
 -29(SR) = .026 [0.66mm]
 -30(SM) = .026 [0.66mm]

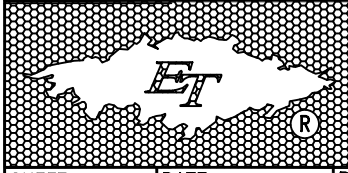
PIN DIAMETER FOR:
 -70(ET) = .0177 [0.45mm]

* All Dimensions Are Nominal For A .050 [1.27mm] Pitch BGA Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 484
LEAD PITCH	= 1.27mm
GRID SIZE	= 26X26
PACKAGE SIZE	= 35.00mm

ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.
 — VLSI and SMT ADAPTERS and ACCESSORIES —

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 FAX:(408)982-0664

SHEET: 1 OF 1 DATE: 08/17/05 REVISION: B **ASSEMBLY DRAWING**

CHECKED: Perry Munroe DRAWN: Huy Nguyen ITEM: S-MBQ-26-484-XX

Scale N/A DO NOT SCALE DRAWING DESCRIPTION: BPQ-484-2BG026-YY